



UG103.06: Bootloader Fundamentals

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This document introduces bootloading for Silicon Labs networking devices. It describes the concepts of standalone and application bootloaders and discusses their relative strengths and weaknesses. In addition, it looks at design and implementation details for each method. Finally, it describes the bootloader file format.

Silicon Labs' *Fundamentals* series covers topics that project managers, application designers, and developers should understand before beginning to work on an embedded networking solution using Silicon Labs chips, networking stacks such as EmberZNet PRO or Silicon Labs *Bluetooth*[®], and associated development tools. The documents can be used as a starting place for anyone needing an introduction to developing wireless networking applications, or who is new to the Silicon Labs development environment.

KEY POINTS

- Introduces the Gecko Bootloader.
- Summarizes the key features the bootloaders support and the design decisions associated with selecting a bootloader.
- Describes bootloader file formats.

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